Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of the claims in the application:

Listing of Claims:

CLAIMS

- 1. (Currently amended) A polish pad comprising:
 - a base layer; and
 - an ion exchange layer disposed in the base layer -; and
- a base support layer, wherein at least one of the base layer and the base support layer is patterned.
- (Original) The polish pad of claim 1, wherein the ion exchange layer comprises ion exchange resin beads.
- 3. (Original) The polish pad of claim 1, wherein the ion exchange layer comprise ground ion exchange resin beads.
- (Currently amended) The polish pad of claim 2, wherein the ion exchange beads are embedded in pressed into the ion exchange layer.
- 5. (Currently amended) The polish pad of claim 3, wherein the ground ion exchange beads are embedded in pressed into the ion exchange layer.
- 6.-9. (Canceled)
- 10. (Original) The polish pad of claim 1, wherein the ion exchange layer binds cations.
- 11. (Original) The polish pad of claim 10, wherein the ion exchange layer binds copper cations.
- 12. (Currently Amended) An ion exchange polish pad comprising
 - a base layer; and
- a resin layer having ion exchange material embedded therein, wherein at least one of the base layer and the resin layer is patterned.

- 13. (Original) The ion exchange polish pad of claim 12, wherein the ion exchange material is ion exchange resin beads.
- 14. (Original) The ion exchange polish pad of claim 12, wherein the ion exchange material is ion exchange resin powder.

15-17 (Cancelled)

18-32 (Previously cancelled)